

MAZ9xxxH Series

Silicon planar type

For surge absorption circuit

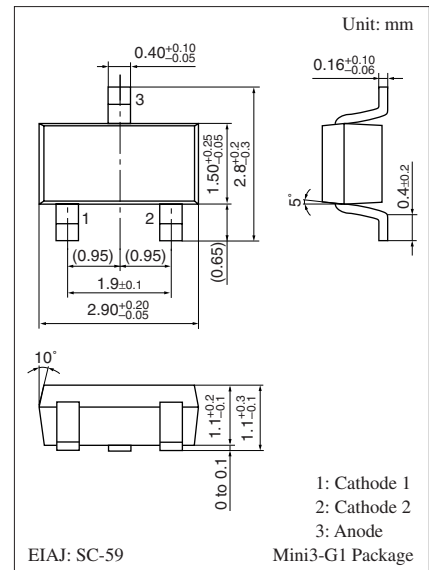
■ Features

- Two elements anode-common type
- Power dissipation P_D : 200 mW

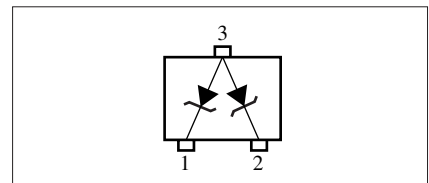
■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation *	P_D	200	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *: $P_D = 200$ mW achieved with a printed circuit board.



Internal Connection



■ Common Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Zener voltage*	V_Z	I_Z Specified value				V
Zener rise operating resistance	R_{ZK}	I_Z Specified value				Ω
Zener operating resistance	R_Z	I_Z Specified value				Ω
Reverse current	I_R	V_R Specified value				μA

Refer to the list of the electrical characteristics within part numbers

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Electrostatic breakdown voltage: ± 10 kV

Test method: IEC1000-4-2 (C = 150 pF, R = 330 Ω , Contact discharge: 10 times)

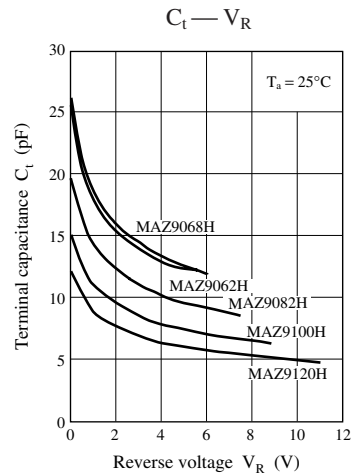
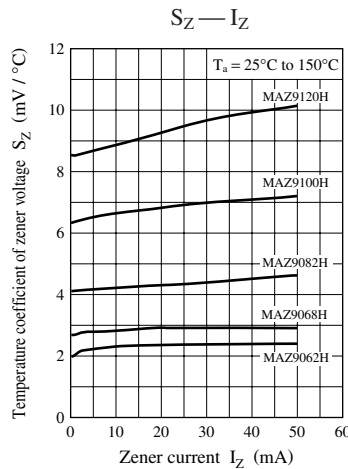
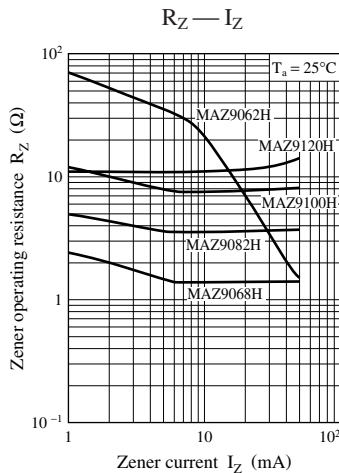
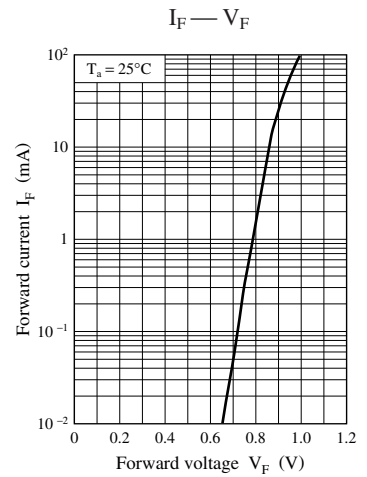
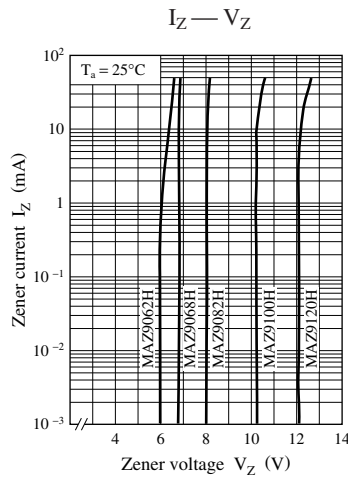
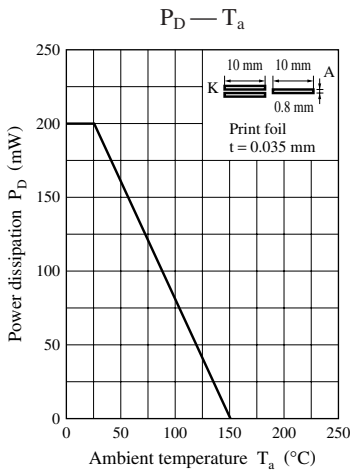
3. *: The temperature must be controlled 25°C for V_Z measurement.

V_Z value measured at other temperature must be adjusted to $V_Z (25^\circ\text{C})$

V_Z guaranteed 20 ms after current flow.

■ Electrical characteristics within part numbers $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Part number	Zener voltage V_Z (V)				Reverse current I_R (mA)		Zener operating resistance R_Z (Ω)	Zener rise operating resistance R_{ZK} (Ω)	Marking symbol
	Min	Nom	Max	I_Z (mA)	Max	V_R (V)	$I_Z = 5$ mA	$I_Z = 0.5$ mA	
							Max	Max	
MAZ9062H	5.8	6.2	6.6	5	0.2	4	50	100	6.2Z
MAZ9068H	6.4	6.8	7.2	5	0.1	4	30	60	6.8Z
MAZ9082H	7.7	8.2	8.7	5	0.1	5	30	60	8.2Z
MAZ9100H	9.4	10.0	10.6	5	0.05	7	30	60	10Z
MAZ9120H	11.4	12.0	12.7	5	0.05	9	30	80	12Z



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